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ABSTRACT

The present invention provides a resin paste which has a sufficient hot adhesion strength and gives a cured product of low elastic modulus, and thereby, causes no chip cracking or warpage and resultantly no property deterioration of IC or the like even when used for bonding of a large chip (e.g. IC) to copper frame or the like, and which is rapidly-curable, and generates no void. That is, the present invention lies in a die-attaching paste comprising, as essential components:

(A) a liquid epoxy resin comprising (a1) an epoxy resin containing chlorine in an amount of 500 ppm or less and having a viscosity of 5,000 mPa·s or less at 25°C and (a2) an epoxy group-containing reactive diluent containing chlorine in an amount of 300 ppm or less and having a viscosity of 1,000 mPa·s or less at 25°C, the weight ratio of (a1):(a2) being 40:60 to 90:10,

(B) a phenol compound having at least two hydroxyl groups in the molecule,

(C) a latent curing agent,

(D) an imidazole compound, and

(E) an inorganic filler.

The present invention also lies in a semiconductor device produced by using the above die-attaching paste.

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